

| LTM2987-BGA 144LD 15mm X 15mm X 3.42mm (TABLE OF MATERIAL DECLARATION) | | | | | | | |
|---|---------------------------|---------------|-------------------------|--|--|----------------------|-------------------------------|
| The LTM2987 is RoHS compliant per EU RoHS Directive 2003/95/EC. It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE) | | | | | | | |
| No. | Part Name | Material Name | Component Weight (gram) | Materials Analysis (element) | CAS Number | Material Mass (gram) | Materials Analysis (weight %) |
| 1 | Substrate | Circuit Board | 0.1859 | Barium Compounds | 7727-43-7 | 0.00364 | 1.96 |
| | | | | Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline) | 105391-33-1,1156-51-0/9003-36-5/21645-51-2, non-disclosure | 0.03313 | 17.82 |
| | | | | Copper Metal | 7440-50-8 | 0.11223 | 60.37 |
| | | | | Copper Compounds | 147-14-8 | 0.00003 | 0.02 |
| | | | | Ecotoxic substances | 7440-38-2, 7439-92-1 | 0.00001 | 0.01 |
| | | | | Phosphorus | 7723-14-0 | 0.00020 | 0.11 |
| | | | | Palladium | 7440-05-3 | 0.00003 | 0.02 |
| | | | | Gold metal or alloy | 7440-57-5 | 0.00011 | 0.06 |
| | | | | Nickel | 7440-02-0 | 0.00231 | 1.24 |
| | | | | Zinc | 7440-66-6 | 0.00014 | 0.07 |
| | | | | Continuous Filament Fiber Glass | 65997-17-3 | 0.02605 | 14.01 |
| | | | | Acrylic Resin | non-disclosure | 0.00693 | 3.73 |
| | | | | Chromium(III) Oxide | 1308-38-9 | 0.00000 | 0.00 |
| | | | | Silica amorphous | 7631-86-9 | 0.00004 | 0.02 |
| | | | | Talc;not containing fibers like asbestos | 14807-96-6 | 0.00043 | 0.23 |
| | | | | Aromatic Carbonyl compounds | non-disclosure | 0.00039 | 0.21 |
| | | | | Cyanoguanidine | 461-58-5 | 0.00001 | 0.01 |
| | | | | Amine compounds | non-disclosure | 0.00005 | 0.03 |
| | | | | Leveling agent and others | non-disclosure | 0.00016 | 0.09 |
| 2 | Solder Paste | Alloy | 0.0293 | Sn | 7440-31-5 | 0.02782 | 95.00 |
| | | | | Sb | 7440-36-0 | 0.00146 | 5.00 |
| 3 | Epoxy | | 0.0121 | Di-ester resin | non-disclosure | 0.00121 | 10.00 |
| | | | | Functionalized ester | non-disclosure | 0.00121 | 10.00 |
| | | | | Silver | 7440-22-4 | 0.00966 | 80.00 |
| 4 | Passive/Active Components | | 0.0628 | Copper (Cu) | 7440-50-8 | 0.02010 | 32.00 |
| | | | | Nickel (Ni) | 7440-02-0 | 0.00502 | 8.00 |
| | | | | Tin (Sn) | 7440-31-5 | 0.00151 | 2.40 |
| | | | | Ceramic (Ba) Compounds | non-disclosure | 0.03617 | 57.60 |
| 5 | Active Ics | Silicon | 0.0158 | Silicon | 7440-21-3 | 0.01584 | 100.00 |
| 6 | Wire | Gold | 0.0024 | Au | 7440-57-5 | 0.00242 | 99.99 |
| 7 | Solder Ball | SAC305 | 0.2451 | Sn | 7440-31-5 | 0.23651 | 96.50 |
| | | | | Ag | 7440-57-5 | 0.00735 | 3.00 |
| | | | | Cu | 7440-50-8 | 0.00123 | 0.50 |
| 8 | Encapsulation | Epoxy Resin | 1.0468 | Fused Silica | 60676-86-0 | 0.80814 | 77.20 |
| | | | | Epoxy Resin | non-disclosure | 0.09317 | 8.90 |
| | | | | Phenol Resin | non-disclosure | 0.09317 | 8.90 |
| | | | | Crytalline Silica | 14808-60-7 | 0.03140 | 3.00 |
| | | | | Carbon Black | 1333-86-4 | 0.00523 | 0.50 |
| | | | | Metal Hydroxide | non-disclosure | 0.01570 | 1.50 |
| Total Package Weight | | | 1.6003 | | | | |

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts